

FIG. 1

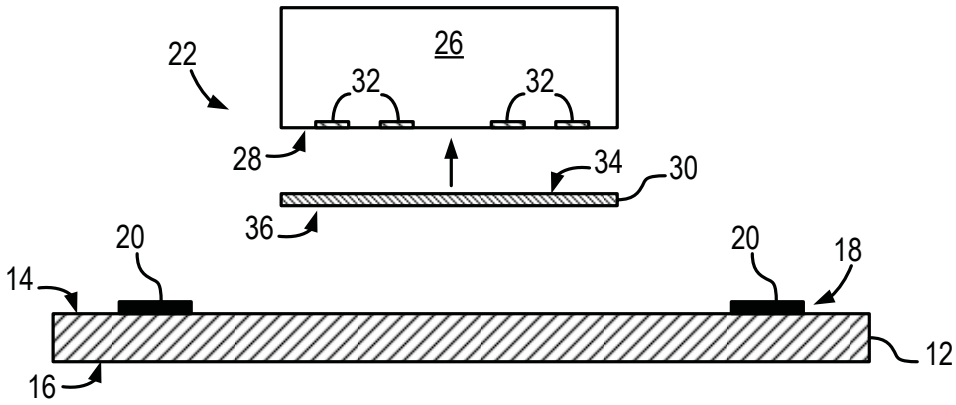


FIG. 2

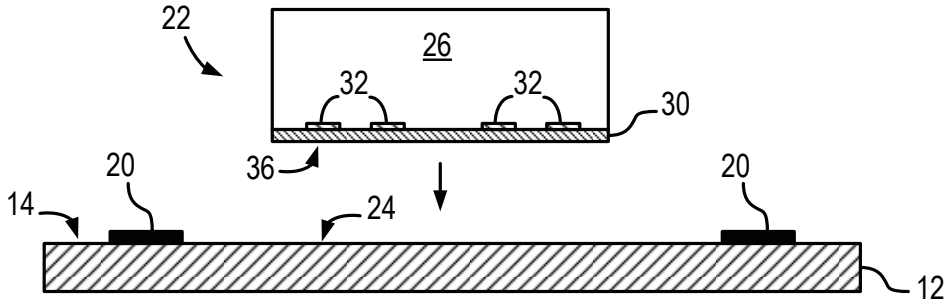


FIG. 3

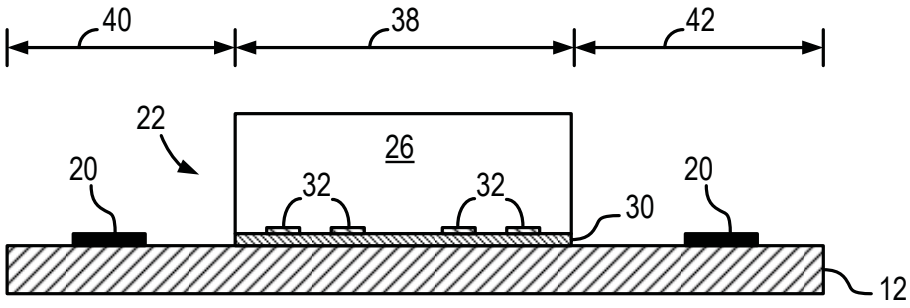


FIG. 4

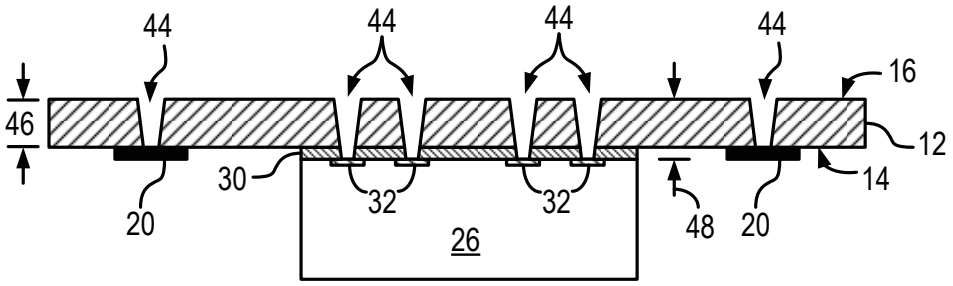


FIG. 5

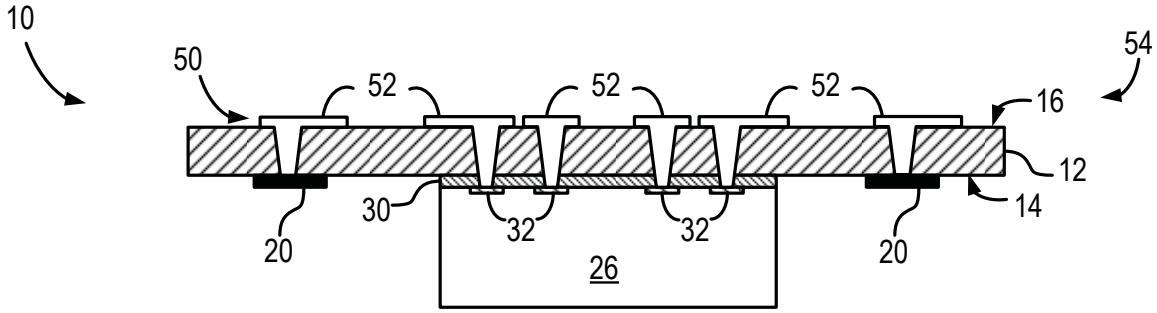


FIG. 6

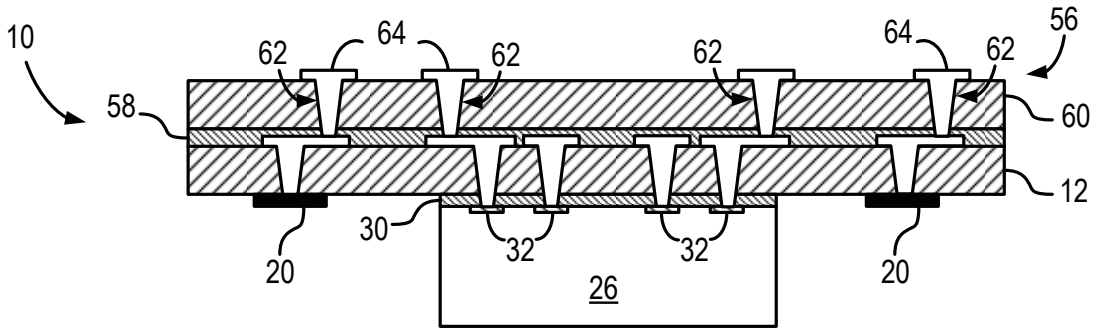


FIG. 7

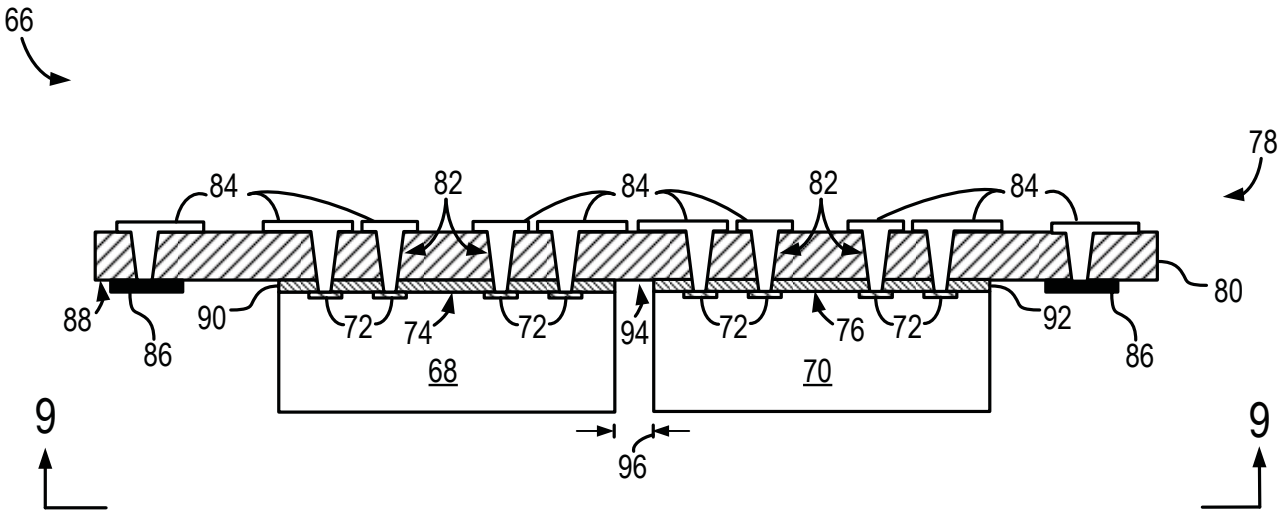

66
78
84
82
84
82
84
80
88
86
90
72
74
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94
72
76
72
92
86
68
70
9
9
96

FIG. 8

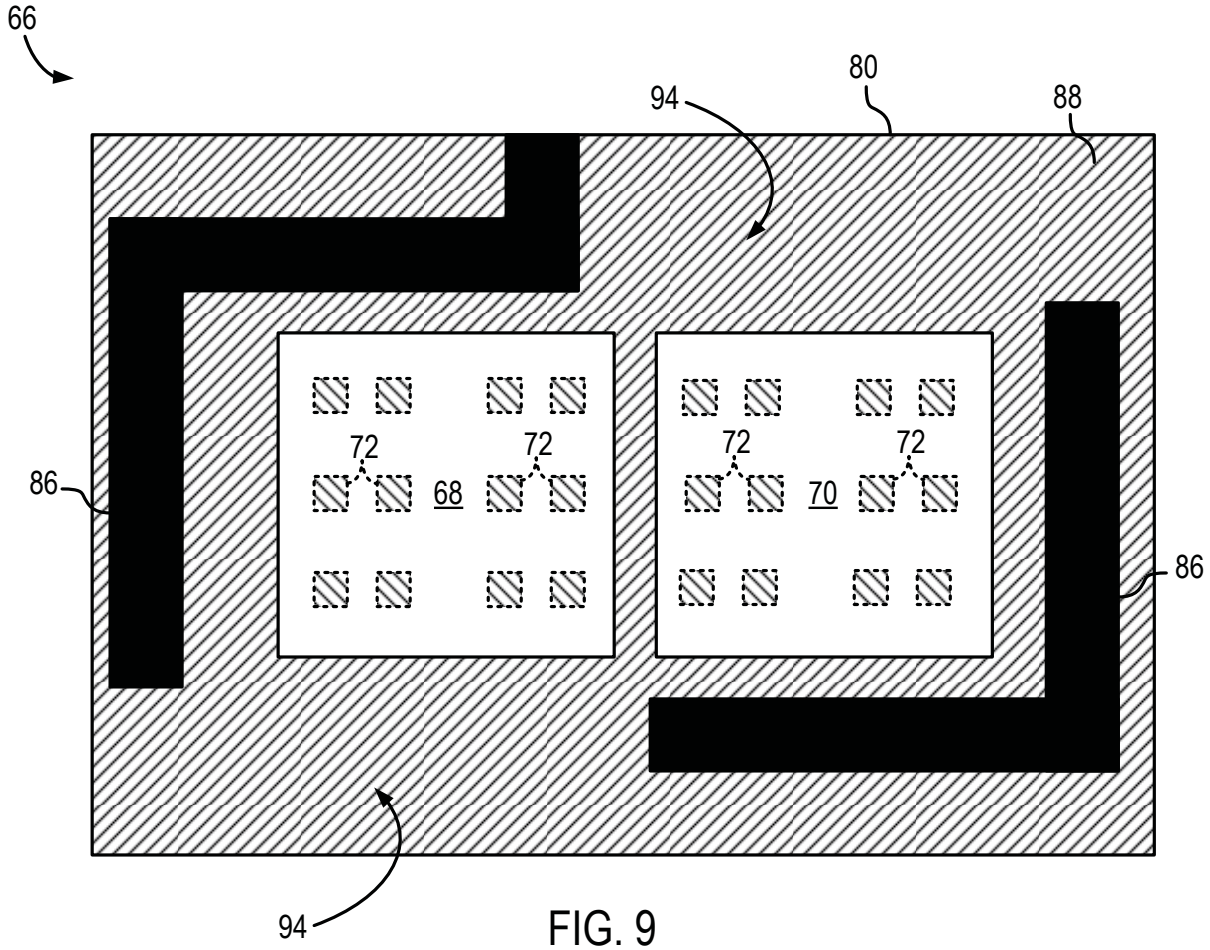

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72
72
72
86
68
70
86
94

FIG. 9

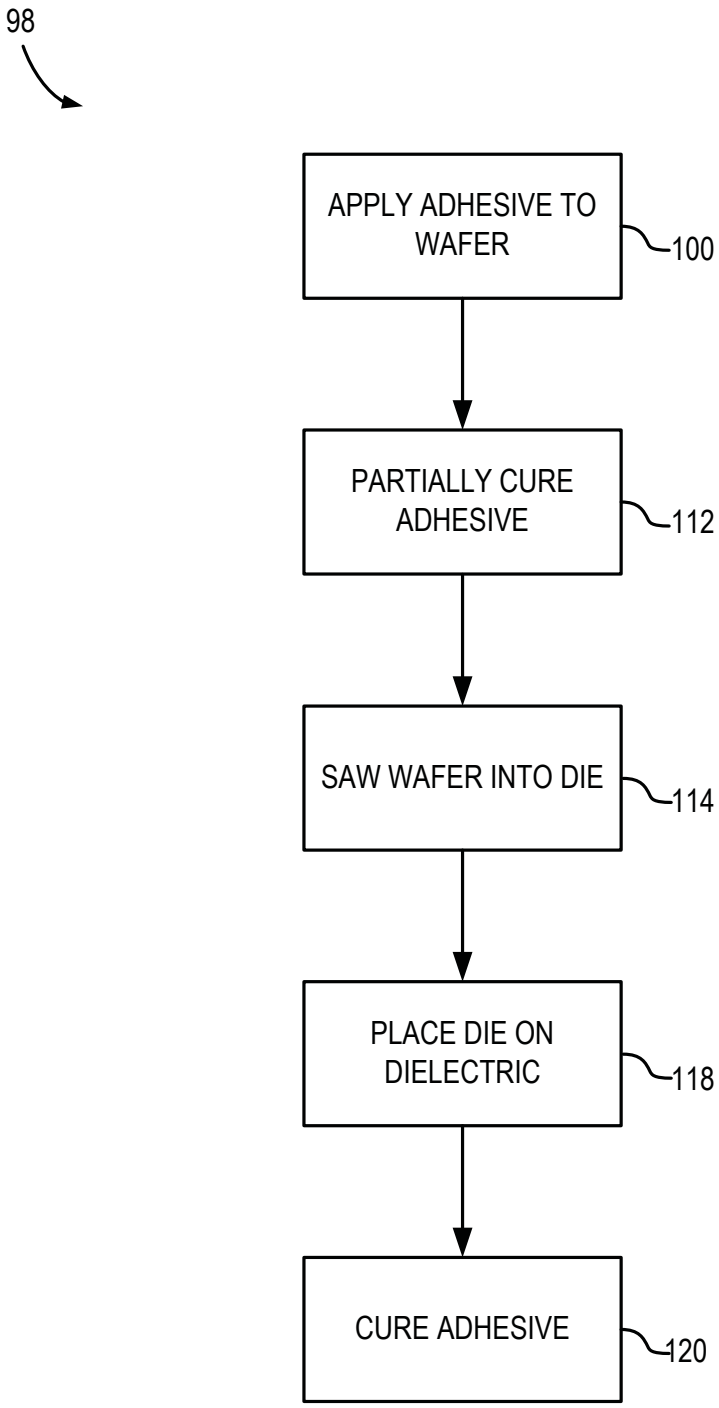

98
APPLY ADHESIVE TO WAFER
100
PARTIALLY CURE ADHESIVE
112
SAW WAFER INTO DIE
114
PLACE DIE ON DIELECTRIC
118
CURE ADHESIVE
120

FIG. 10

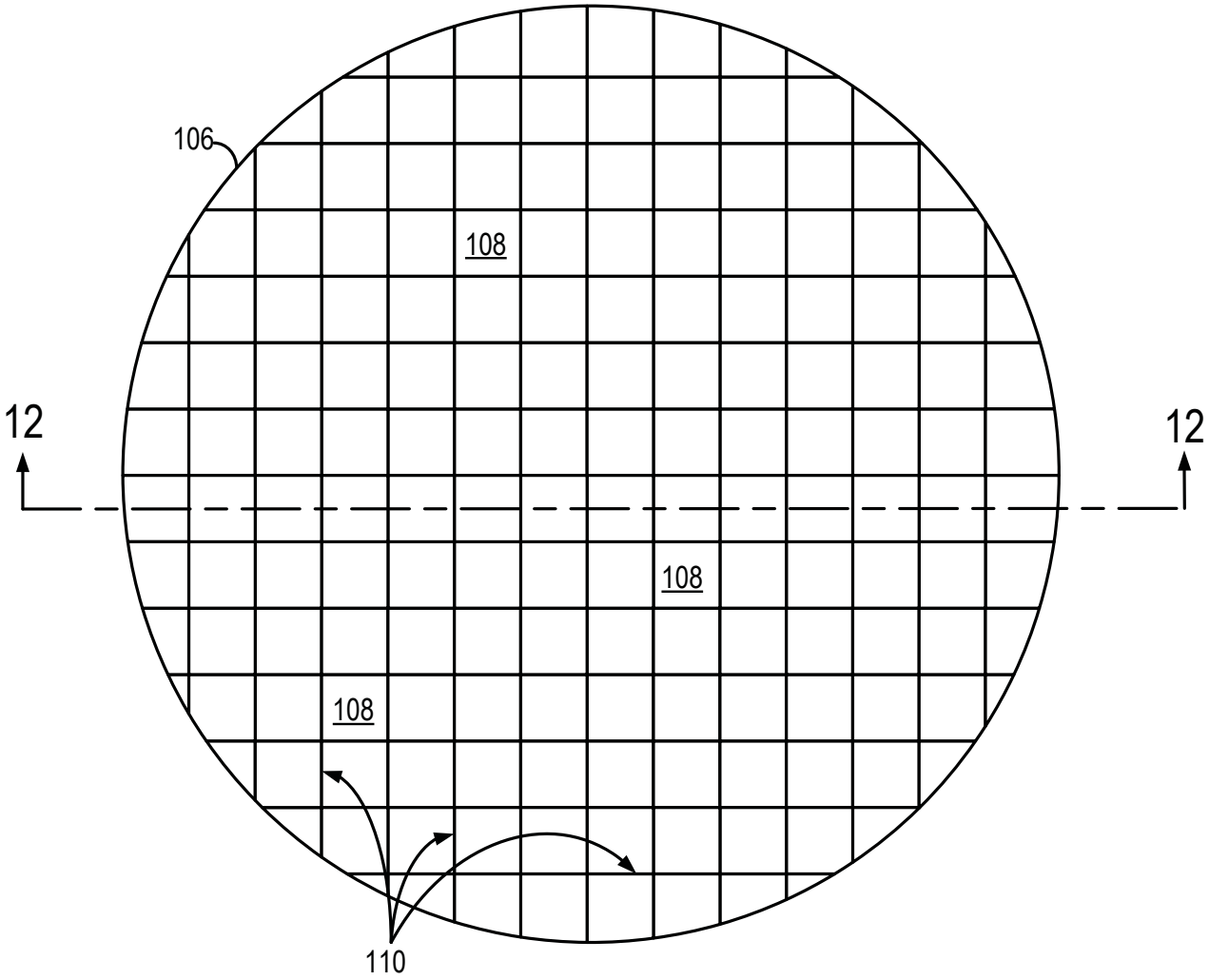


FIG. 11

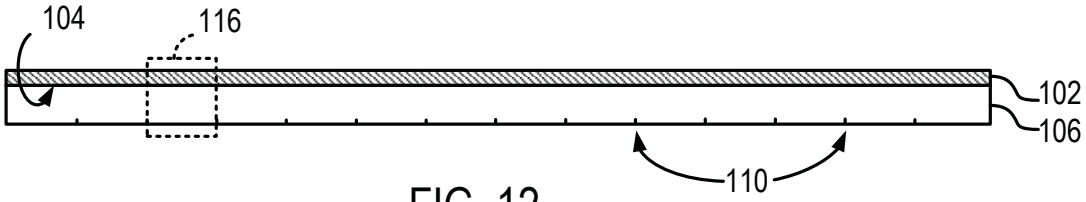


FIG. 12

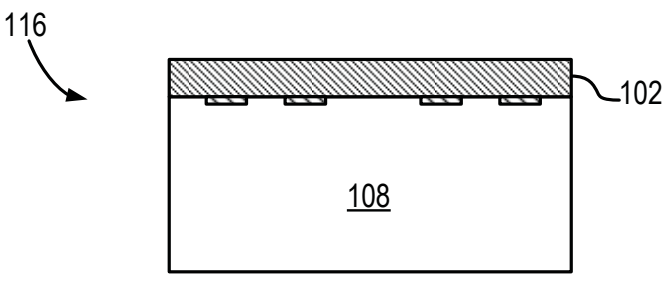


FIG. 13

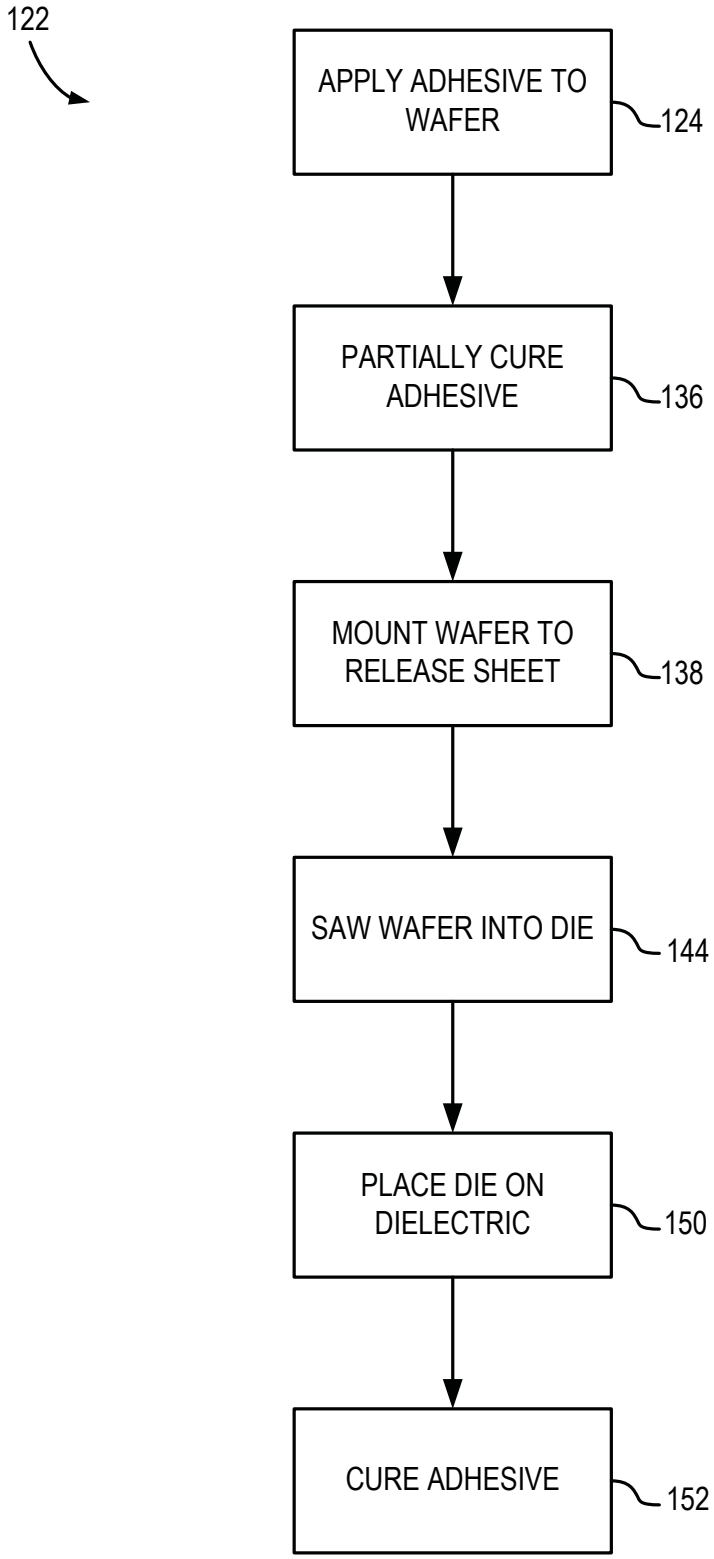

122
APPLY ADHESIVE TO WAFER
124
PARTIALLY CURE ADHESIVE
136
MOUNT WAFER TO RELEASE SHEET
138
SAW WAFER INTO DIE
144
PLACE DIE ON DIELECTRIC
150
CURE ADHESIVE
152

FIG. 14

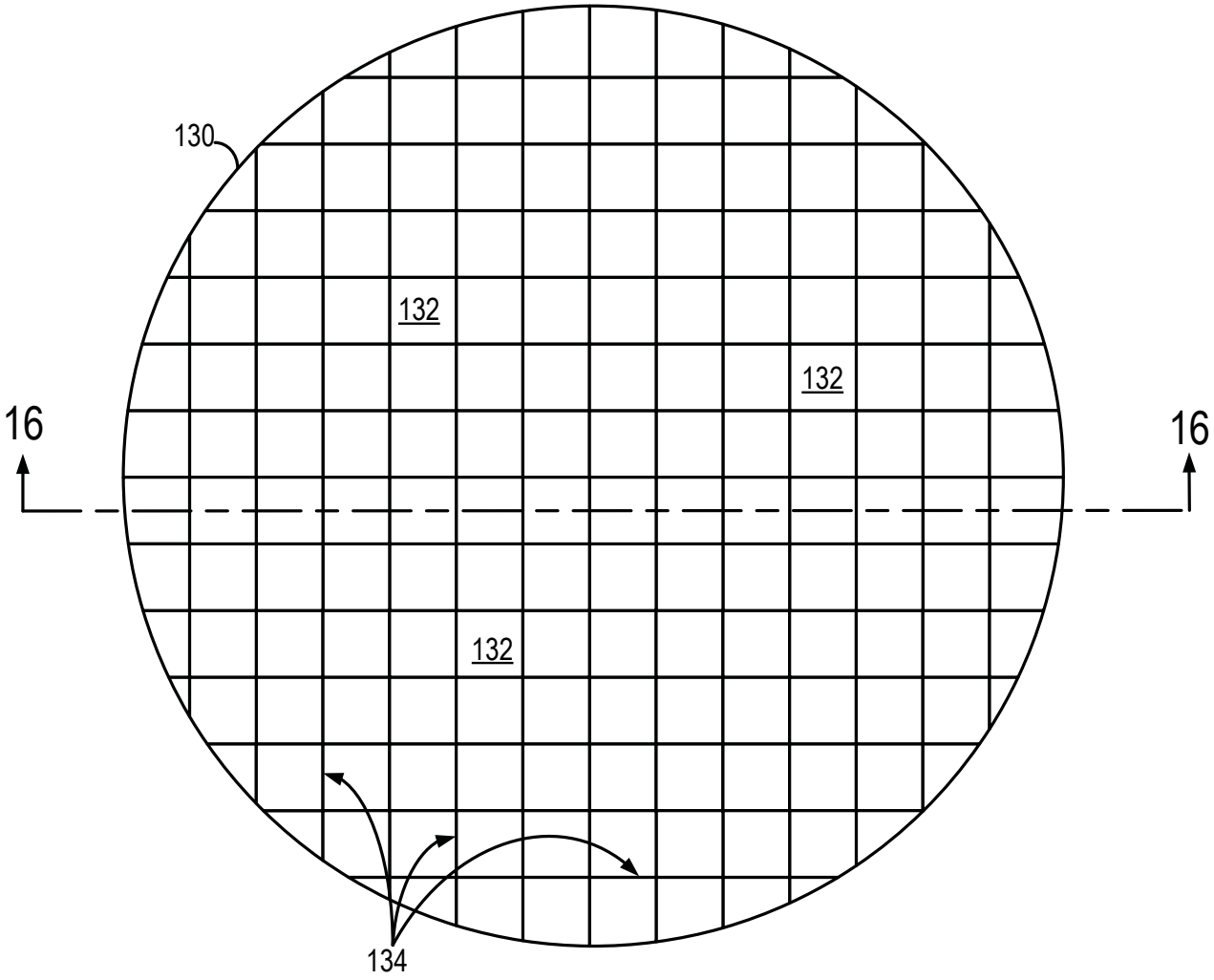


FIG. 15

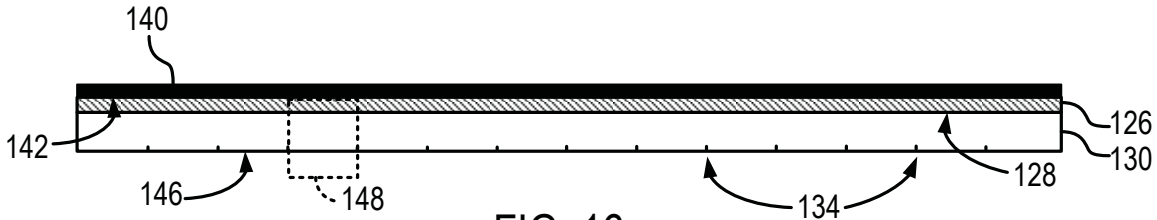


FIG. 16

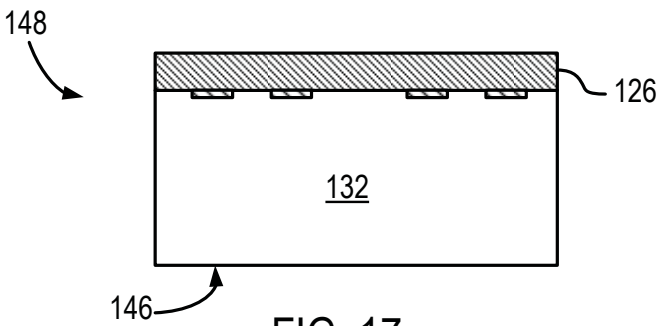


FIG. 17

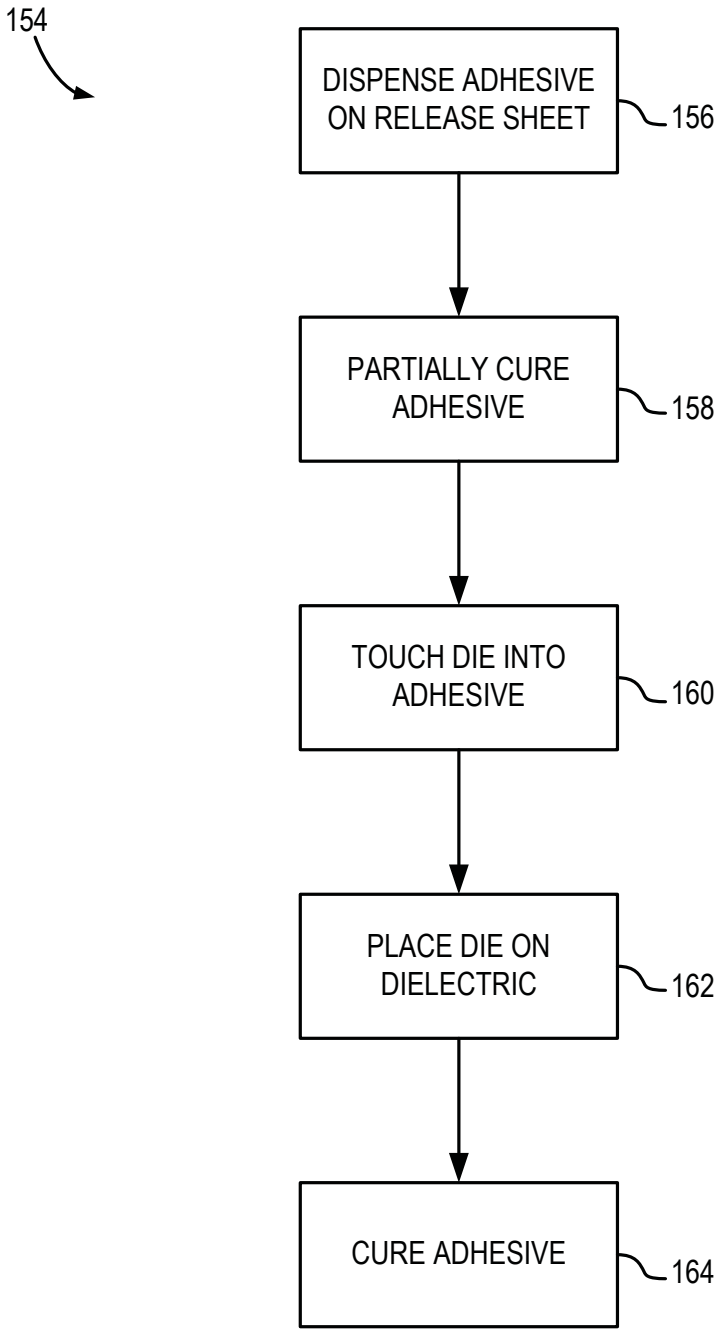

154
DISPENSE ADHESIVE ON RELEASE SHEET
156
PARTIALLY CURE ADHESIVE
158
TOUCH DIE INTO ADHESIVE
160
PLACE DIE ON DIELECTRIC
162
CURE ADHESIVE
164

FIG. 18

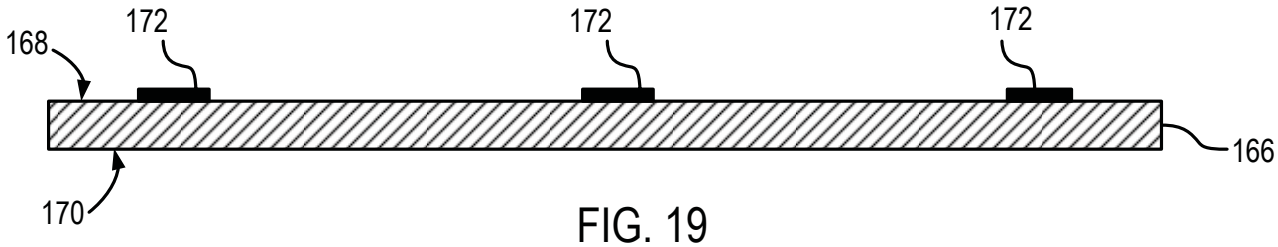


FIG. 19

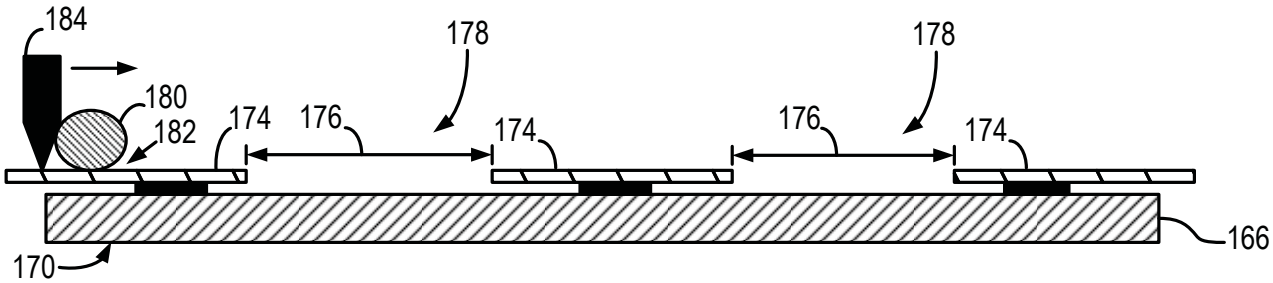


FIG. 20

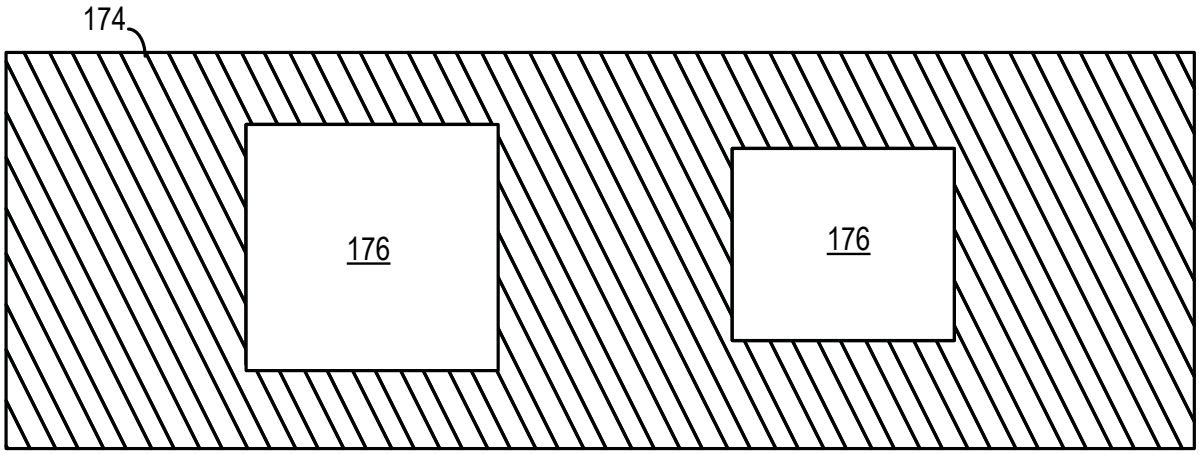


FIG. 25

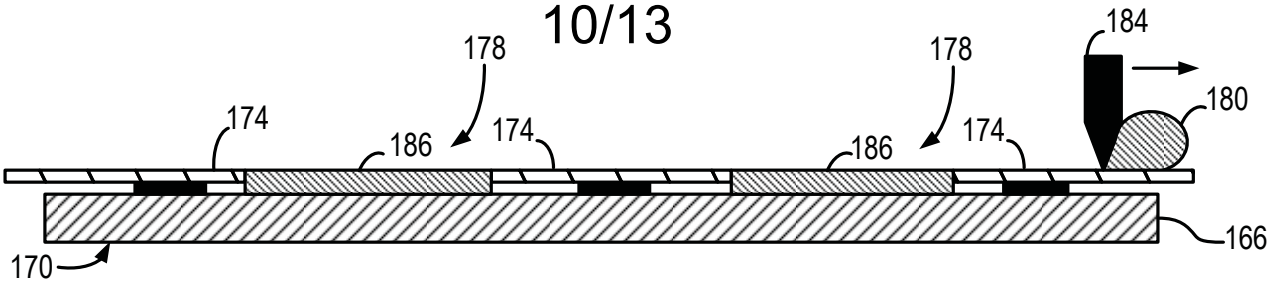


FIG. 21

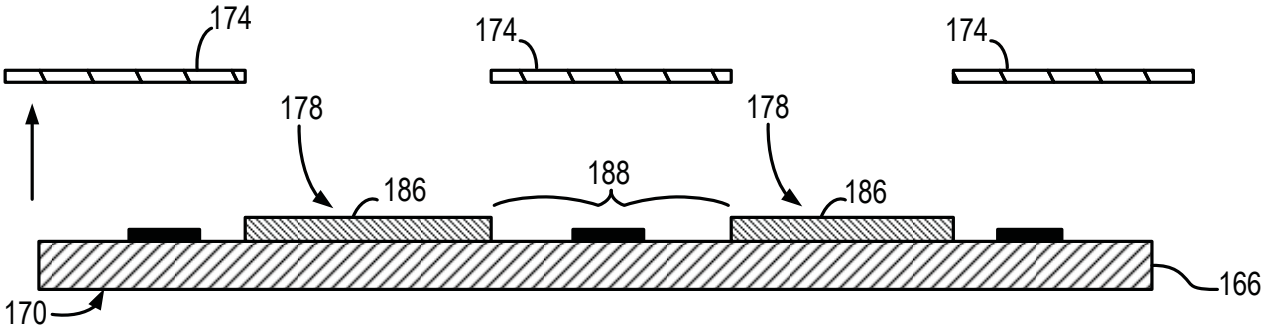


FIG. 22

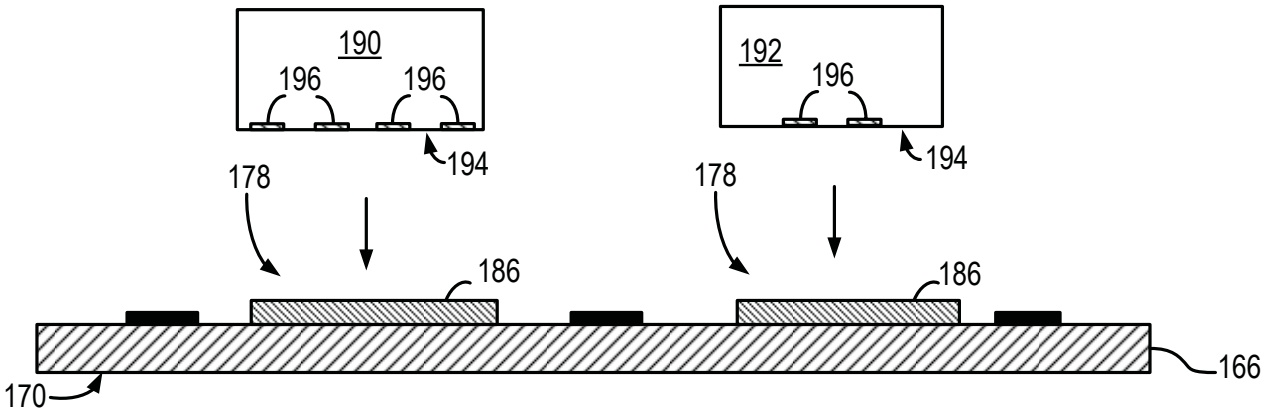


FIG. 23

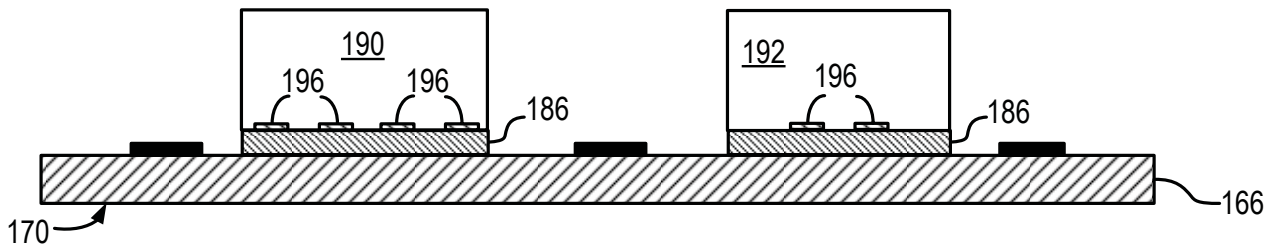


FIG. 24

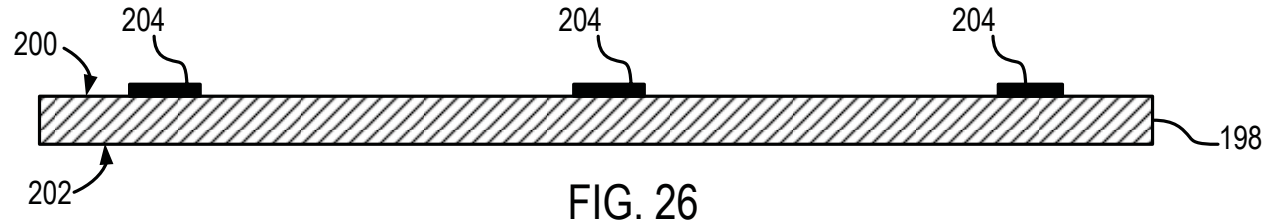


FIG. 26

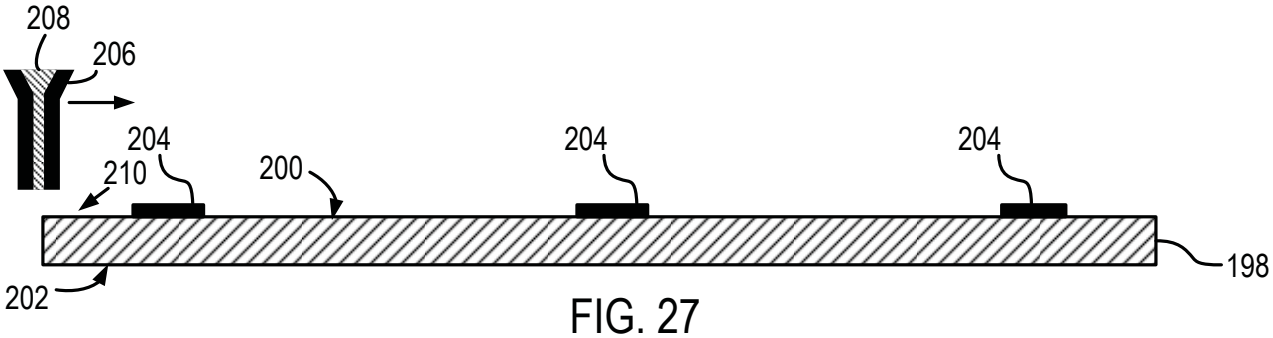


FIG. 27

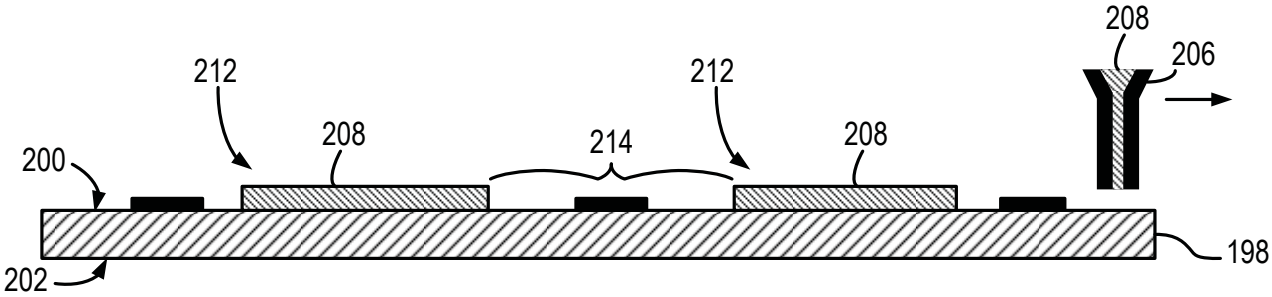


FIG. 28

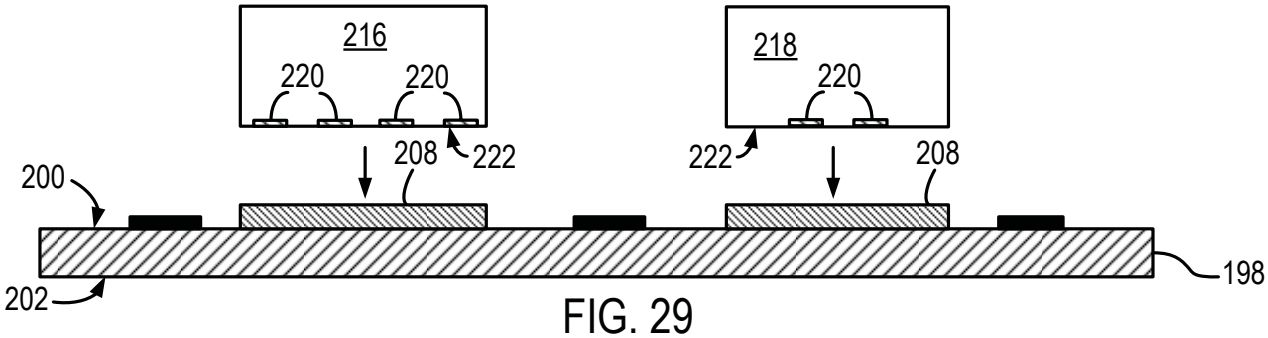


FIG. 29

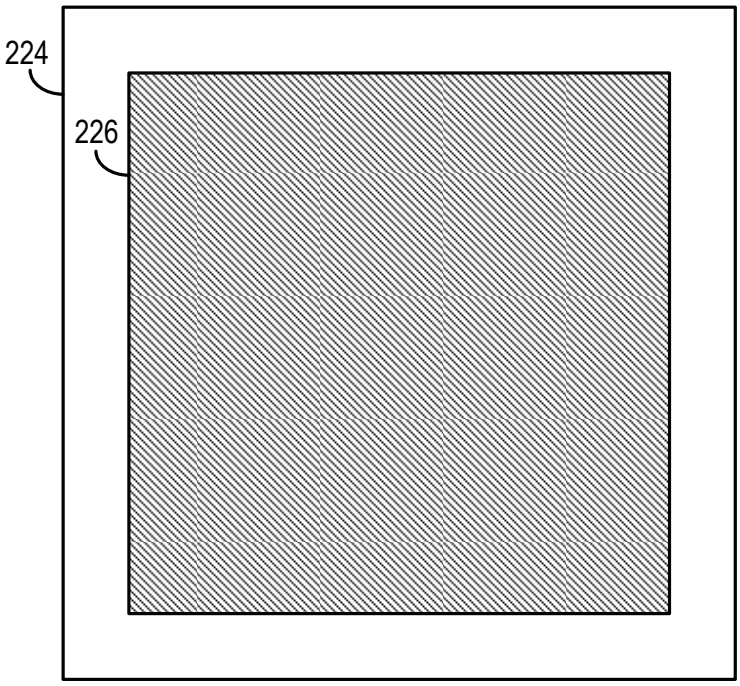


FIG. 30

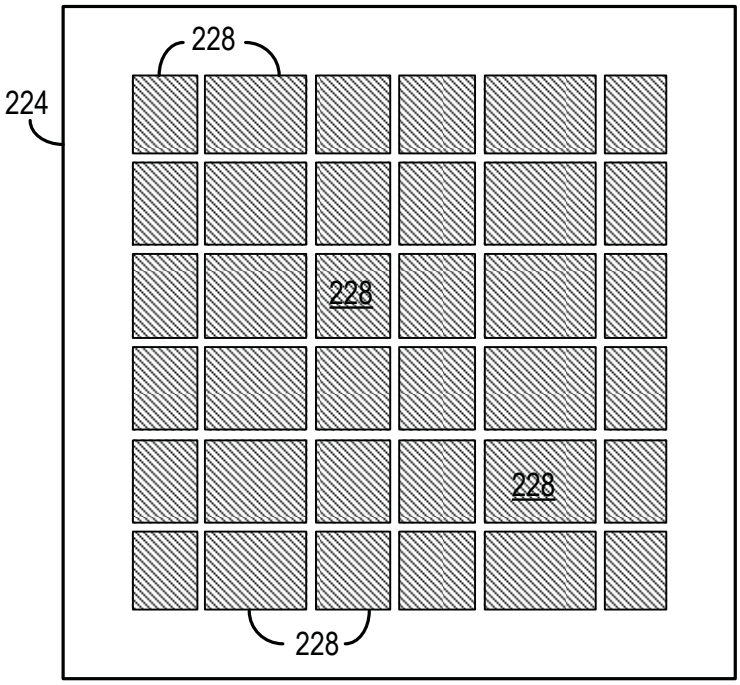


FIG. 31

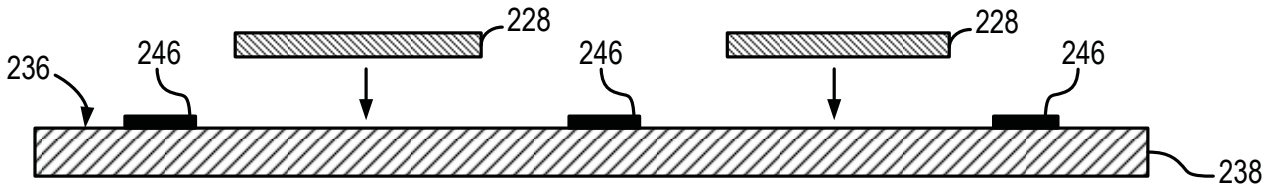


FIG. 32

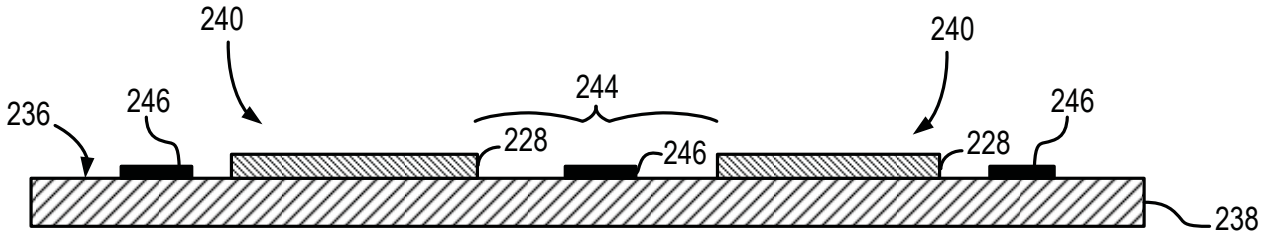


FIG. 33

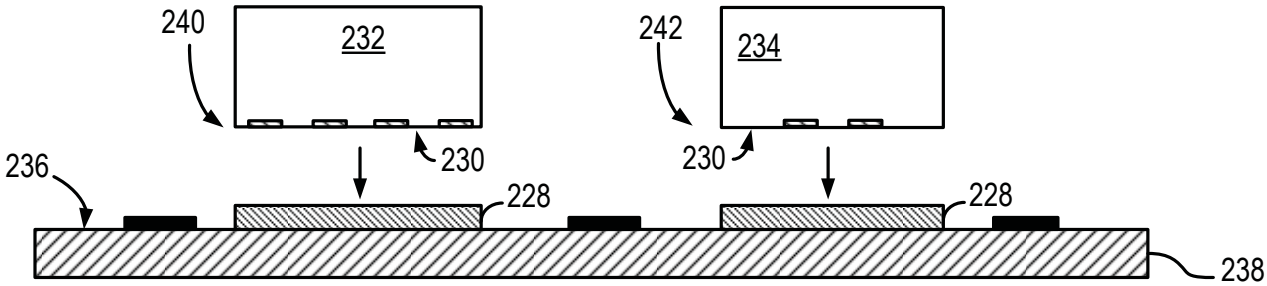


FIG. 34

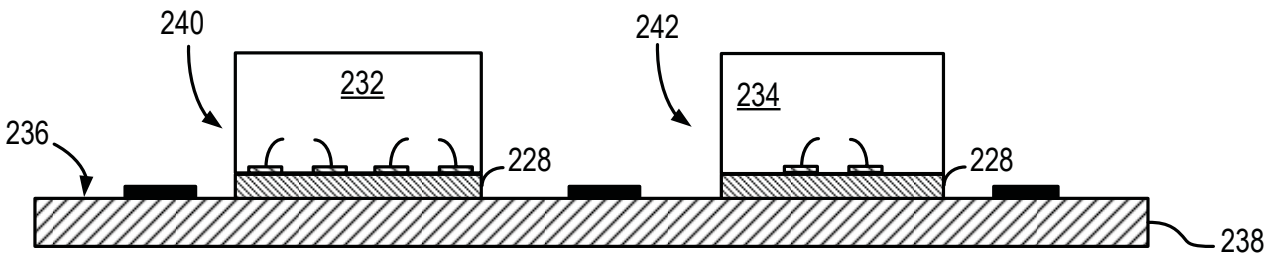


FIG. 35